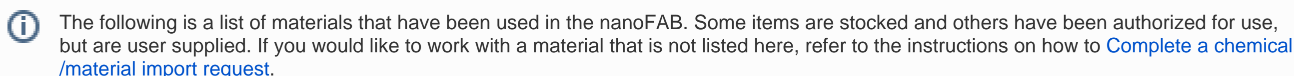
Safety Data Sheet (SDS) Repository



The following is a list of materials that have been used in the nanoFAB. Some items are stocked and others have been authorized for use, but are user supplied. If you would like to work with a material that is not listed here, refer to the instructions on how to Complete a chemical /material import request.

Material	Composition	Product	Synonyms	Status
2D_CL_PC polymer solution	94% chloroform, 6 % polycarbonate; liquid	2D_CL_PC polymer solution		RESTRICTED USE
A-174 silane	70–100% 3-trimethoxysilylpropyl methacrylate, 0.1–1% 4-methoxy-phenol; liquid	A-174 silane	gamma-methacryloxypropyltrimethoxysilane, gamma-MAPS, 3-(trimethoxysilyl)propyl methacrylate	STOCKED
Acetone	100% acetone; liquid	Acetone	2-propanone, propanone, dimethyl ketone	STOCKED
Air Zero (zero air)	100% Air	Air Zero	Air, Medipure Air, Plasma Air, Zero Air, Air - Diving Grade	STOCKED
Aluminum etch	Nitric acid, Phosphoric acid, Acetic acid, Water	Aluminum Etchant Type A		STOCKED
Ammonia	99.5 - 100% ammonia; gas	Ammonia	NH_3	
Anisole	100% anisole; liquid	Anisole	methoxybenzene, methyl phenyl ether, ZEP-A	STOCKED
AQM SiOx	100% hydrogen silsesquioxane based polymer; solid	AQM SiOx	HSQ	STOCKED
Argon	99.5% - 100% Argon	Argon Ar	Shielding gas, Argon 40, Extendapak Argon	STOCKED
AR-P 6200	>80% anisole, 20% poly(-methyl styrene-co--chloroacrylate methylester); liquid	E-Beam Resist AR-P 6200 series	CSAR 62	
AZ 12XT-20PL-10 photoresist	55–60% 1-Methoxy-2-propanol acetate, 20–25% Non-hazardous styrene-acrylate polymer, <0.3% 2-Methoxy-1-propanol acetate, 15–20% Cresol novolak resin; liquid	AZ 12XT-20PL-10 photoresist	AZ 12XT	
AZ 15nXT (450 CPS) photoresist	1–3% 1,8-Naphthalimidyl triflate, 0.1–0.3% 2-Methoxy-1-propanol acetate, 50–100% 1-Methoxy-2-propyl acetate; liquid (only hazardous components listed)	AZ 15nXT (450 CPS) photoresist	AZ 15nXT	
AZ 300 MIF Developer	>95% water, <3% tetramethylammonium hydroxide; liquid	AZ 300 MIF Developer		

AZ 400K 1:4 Developer	>95% water, <2% potassium borates; liquid	AZ 400K Developer Diluted 1:4	AZ 400K	STOCKED
AZ 1512 photoresist	75–100% 1-Methoxy-2-propanol acetate, 5% Diazonaphthoquinonesulfonic ester, 19% Cresol novolak resin; liquid	AZ 1512 photoresist		STOCKED
AZ 1529 photoresist	65–70% 1-Methoxy-2-propanol acetate, 5–10% Diazonaphthoquinone sulfonic ester, 0 - 0.3% 2-Methoxy-1-propanol acetate, 25–30% Cresol novolak resin; liquid	AZ 1529 photoresist		STOCKED
AZ 5214E photoresist	70–75% 1-Methoxy-2-propanol acetate, 1–5% Diazonaphthoquinonesulfonic ester, <0.3% 2-Methoxy-1-propanol acetate, 20–25% Cresol novolak resin, <2% Phenolic compound; liquid	AZ 5214E photoresist		STOCKED
AZ 9260 photoresist	55–60% 1-Methoxy-2-propanol acetate, 5% Diazonaphthoquinonesulfonic ester, <0.3% 2-Methoxy-1-propanol acetate, 35–40% Cresol novolak resin; liquid	AZ 9260 photoresist		
AZ Developer 1:1	99% water, 1% sodium metasilicate; liquid	AZ Developer 1:1	AZDEV 1:1	STOCKED
AZ P4260 photoresist	60–65% 1-Methoxy-2-propanol acetate, 1–5% Diazonaphthoquinonesulfonic ester, 30–35% Cresol novolak resin; liquid	AZ P4260 photoresist		STOCKED
AZ P4330-RS photoresist	65–70% 1-Methoxy-2-propanol acetate, 1–5% Diazonaphthoquinonesulfonic ester, <0.3% 2-Methoxy-1-propanol acetate, 25–30% Cresol novolak resin; liquid	AZ P4330-RS photoresist		
Bleach	94–98.9% water, 1–5% sodium hypochlorite, 0.1–1% sodium hydroxide; liquid	Clorox Clean-Up Cleaner + Bleach - Original		
Boron Trichloride	BCL_3	Boron Trichloride	Inert Gas(es) (Ar, He and/or N) - Boron Trichloride 0.1 ppm - 2.99999%	STOCKED RESTRICTED USE
Boron Trichloride - 3%	3% BCL_3 : 97% N_2	Boron Trichloride - 3%	Inert Gas(es) (Ar, He and/or N) - Boron Trichloride 0.1 ppm - 2.99999%	STOCKED RESTRICTED USE
Buffer Oxide Etchant (BOE)	Hydrofluoric Acid, Ammonium Fluoride, Potassium Perfluoroalkyl Sulfonate, Water	Buffer Oxide Etchant (BOE) with Surfactant	10:1 BOE	STOCKED RESTRICTED USE
Calcium Chloride 83% Flake	Calcium Chloride, Water, Potassium Chloride, Sodium Chloride	Calcium Chloride 83% Flake		STOCKED

Calcium Chloride 83% Flake	Calcium Chloride, Water, Potassium Chloride, Sodium Chloride	Calcium Chloride 83% Flake		STOCKED
Carbon Dioxide	99.5 - 100 % Carbon Dioxide	Carbon Dioxide - CO_2	Medipure® Carbon Dioxide, Extendapak® EX-2, Refrigerant gas R744, carbonic anhydride, carbonic acid gas	STOCKED
Cellulose acetate	100% cellulose acetate; solid	Cellulose acetate	Acetylcellulose	
Cellulose acetate solution in ethyl acetate	5–20 wt.% cellulose acetate, 80–95 wt.% ethyl acetate; liquid	Cellulose acetate solution in ethyl acetate		RESTRICTED USE
Chlorine	100% Chlorine	Chlorine - Cl_2		STOCKED RESTRICTED USE
Chrome Mask Etchant 9030	4–6% perchloric acid, 6–8% ceric ammonium nitrate, 86–90% water; liquid	Chrome Mask Etchant 9030	chrome etch	STOCKED
Chromium Cermat Etchant TFE	20% potassium hexacyanoferrate, 10% sodium hydroxide, 70% water; liquid	Chromium Cermat Etchant TFE	chrome etch	STOCKED
Cobalt iron	10–90% cobalt, 90–10% iron; solid	Cobalt iron (sputtering target)	CoFe	
Cobalt iron boron	60% cobalt, 20% iron, 20% boron; solid	Cobalt iron boron (sputtering target)	CoFeB	
Cyclohexanone	100% cyclohexanone; liquid	Cyclohexanone	ketohexamethylene, pimelic ketone, sextone	
CYTOP CT-SOLV100E	>99% 1,1,1,2,2,3,4,5,5,5-decafluoro-3-methoxy-4-(trifluoromethyl)-pentane; liquid	CYTOP CT-SOLV100E	3-methoxyperfluoro(2-methylpentane)	
CYTOP CT-SOLV180	90–95% perfluorotributylamine, 5-10% unidentified impurities; liquid	CYTOP CT-SOLV180	perfluorotributylamine, perfluorotrialkylamine	
CYTOP CTXSP2	85–99% Perfluorotributylamine, 1-15% Poly-1,1,2,4,4,5,5,6,7,7-decafluoro-3-oxa-1,6-heptadiene; liquid	CYTOP CTX-8**SP2 (** = 01 ~ 15)	Perfluorinated solvent	
CN carbon nitride	100% CN carbon nitride; solid (powder)	CN carbon nitride		RESTRICTED USE
Deionized water	100% deionized water	Deionized water	water, DI, DI water, hydrogen oxide, dihydrogen oxide	STOCKED

Dessicant - Silica Gel Beads	>99% Amorphous Silica, 0.2-0.9% Cobalt Dichloride	Dessicant	Drican, DRI-BOX, Indicating Silica	STOCKED RESTRICTED USE
Developer AR 600-549	90% diethyl malonate, <10% anisole; liquid	Developer AR 600-549		
Dichlorosilane (DCS)	SiH_2Cl_2	Dichlorosilane	Chlorosilane A-199, DCS	RESTRICTED USE
Diethanolamine	100% diethanolamine	Diethanolamine	2,2'-iminodiethanol, diolamine, iminodiethanol	RESTRICTED USE All processing must occur in Aisle 1 fumehood.
Diethanolamine aqueous solution	5–10 wt.% diethanolamine, 90–95 wt.% water	Diethanolamine aqueous solution		RESTRICTED USE All processing must occur in Aisle 1 fumehood. Must be spun on in foil-lined Headway spinner.
Diethanolamine aqueous solution	5–10 wt.% diethanolamine, 90–95 wt.% water	Diethanolamine in water solution		RESTRICTED USE All processing must occur in Aisle 1 fumehood. Must be spun on in foil-lined Headway spinner.
Diethylsilane (DES)	>95%	Diethylsilane (DES)	Diethyldihydrosilane, DES	STOCKED RESTRICTED USE
Diiodomethane	100% diiodomethane; liquid	Diiodomethane	MI, methylene iodide, methylene diiodide	RESTRICTED USE
DPP-DTT polymer	100% Poly[3,6-bis(5-thiophen-2-yl)-2,5-bis(2-octyldodecyl)pyrrolo[3,4-c]pyrrole-1,4(2H,5H)-dione-2,2'-diyl-alt-thieno[3,2-b]thiophen-2,5-diyl]; solid	DPP-DTT polymer	PDPP-DTT, Poly-DPP-DTT, DPP DTT polymer, PTT-DTDPP, PDBT-co-DTT	
EKC265	Proprietary amounts of: 2-(2Aminoethoxy) Ethanol, Hydoxylamine, Catechol	EKC265	None	STOCKED RESTRICTED USE
Electra 92		Protective Coating AR-PC 5090+5091 series	Electra 92	STOCKED
EPO-TEK 377 Part A	60–100% bisphenol A diglycidyl ether resin, 30–60% reactive diluent (proprietary); liquid	EPO-TEK 377 Part A	377/A	RESTRICTED
EPO-TEK 377 Part B	60–100% substituted anhydride (proprietary), 1–5% phthalic anhydride; liquid	EPO-TEK 377 Part B	377/B	RESTRICTED
Ethyl acetate	100% ethyl acetate; liquid	Ethyl acetate	ethyl ethanoate, acetic acid ethyl ester, acetoxyethane	RESTRICTED USE All processing must occur in Aisle 1 fumehood.
Ferric chloride	37–42% ferric chloride, 1% hydrochloric acid, <1% ferrous chloride, >61% water; liquid	415 Ferric Chloride	$FeCl_3$, 415, copper etch	STOCKED

Fluorinert FC-72 Electronic Liquid	100% perfluoro compounds, C5-18; liquid	Fluorinert FC-72 Electronic Liquid	perfluorodecane	
FluoroPel PFC1101V	90–99% 1-propene, 1,1,2,3,3,3-hexafluoro-oxidized polymd., 10–1% fluoropolymer (proprietary); liquid	FluoroPel PFC1101V		
Gadolinium iron cobalt	24% gadolinium, 68% iron, 8% cobalt; solid	Gadolinium iron cobalt (sputtering target)	GdFeCo	
Gallium oxide	100% Ga_2O_3; solid	Gallium oxide (sputtering target)	digallium trioxide, gallium trioxide, gallium sesquioxide	
Germanium	100% germanium; solid	Germanium (powder and pieces)	Ge	
Germanium antimony telluride	100% germanium antimony telluride ($Ge_2Sb_2Te_5$); solid	Germanium antimony telluride	GST	RESTRICTED
gNDI-Br2	100% 2,6-Dibromo-N,N'-bis(2-ethoxyethyl-2-(2-(2-methoxyethoxy) ethoxy)acetate)-1,4,5,8-naphthalenetetracarboxylicdiimide; solid	gNDI-Br2		
Helium	100% Helium	Helium - He	Helium-4, refrigerant gas R-704, LaserStar Helium, Medipure Helium, UltraLift Helium, Helium - Diving Grade	STOCKED
HiPco Carbon Nanotubes	100% synthetic graphite; solid (powder)	HiPco™ Carbon Nanotubes	single-called carbon nanotubes, fullerene nanotubes	RESTRICTED USE
HPR 504		HPR 504	504, photoresist	
HPR 506		HPR 506	506, photoresist	
Hydrochloric Acid	HCL < 10%; Water > 90%	Hydrochloric Acid		STOCKED
Hydrofluoric acid	49% hydrogen fluoride, 51% water; liquid	Hydrofluoric acid	49% HF	STOCKED RESTRICTED USE
Hydrogen	100% Hydrogen; gas	Hydrogen	Dihydrogen, parahydrogen, refrigerant gas R702, water gas	
Hydrogen / Inert Gas Mixture	2.93 - 99.9999% Hydrogen; 0 - 94.4999% Nitrogen	Hydrogen / Inert Gas Mixture	forming gas	

Hydrogen Bromide	100% Hydrogen Bromide	Hydrogen Bromide - HBr	Hydrogen bromide, anhydrous	STOCKED RESTRICTED USE
Hydrogen peroxide	25–35% hydrogen peroxide, 65–75% water; liquid	Hydrogen peroxide	peroxide, hydrogen dioxide solution	STOCKED
Hydroxypropyl methylcellulose	100% hydroxypropyl methylcellulose; solid	Hydroxypropyl methylcellulose	Cellulose hydroxypropyl methyl ether	
Hydroxypropyl methylcellulose aqueous solution	5–20 wt.% hydroxypropyl methylcellulose, 80–95 wt.% water; liquid	Hydroxypropyl methylcellulose aqueous solution		RESTRICTED USE
Immersol 518 F	Adipic acid-di(8-methyl-tricyclo (5.2.1.0.2.6.) decane) ester, Benzyl benzoate	Immersol 518 F		STOCKED
Iodine	Iodine	Iodine, resublimed, crystals	Iodine crystals; iodine sublimed	STOCKED
IP-Dip Photoresist		IP-Dip Photoresist	ip-dip	STOCKED
IP-L 780 Photoresist		IP-L 780 Photoresist	IP-L	STOCKED
IP-S Photoresist		IP-S Photoresist	ip-S	STOCKED
Isopropyl alcohol (IPA)	98–100% 2-propanol	Isopropyl alcohol	IPA, isopropanol, 2-propanol	STOCKED
Kapton tape	50–65% Silicone adhesive; 35–50% Polyimide film backing	3M Polyimide Film Tape 5413	Kapton tape	STOCKED
KMPR Photoresist		KMPR Series Photoresist	kmpr	STOCKED
Krypton	99.5% - 100% Krypton	Krypton - Kr	Krypton, compressed	STOCKED
Liquid nitrogen	100% nitrogen; liquid	Nitrogen, refrigerated liquid	LN2, cryogenic liquid	STOCKED
Lithium fluoride	100% lithium fluoride; solid	Lithium fluoride	LiF	RESTRICTED USE
Lithium niobate	100% lithium niobate; solid	Lithium niobate	Lithium niobium trioxide, Lithium niobium oxide,	
LOR 5B resist	65–90% cyclopentanone, 10–15% 1-methoxy-2-propanol, 1–20% polyaliphatic imide copolymer, 0.1–2% proprietary dye B; liquid	LOR 5B (LOR B series resists)	LOR	STOCKED

LOR 5B resist	65–90% cyclopentanone, 10–15% 1-methoxy-2-propanol, 1–20% polyaliphatic imide copolymer, 0.1–2% proprietary dye B; liquid	LOR 5B (LOR B series resists)	LOR	STOCKED
Magnesium oxide	100% magnesium oxide; solid	Magnesium oxide (sputtering target)	MgO	
Manganese iridium	80% manganese, 20% iridium; solid	Manganese iridium (sputtering target)	MnIr	
Methane	100% Methane	Methane	Methyl hydride, Marsh gas, Biogas, Fire Damp	STOCKED RESTRICTED USE
Methanol	methanol	Methanol	wood alcohol, carbinol	
Methyl isobutyl ketone	90–100% 4-methylpentan-2-one; liquid	Methyl isobutyl ketone	MIBK, 4-methyl-2-pentanone, 4-methylpentan-2-one, isopropylacetone, isobutyl methyl ketone, hexone	STOCKED
MIBK-IPA	Isopropyl Alcohol, Methyl Isobutyl Ketone	MIBK/IPA Series Positive Radiation REsist Developers	MIBK	STOCKED
MICROPOSIT 351	water, boron sodium oxide, sodium hydroxide	MICROPOSIT 351 DEVELOPER	351 developer, 351	
Microposit MF-319	95.0–99.0% water, 1.0–5.0% tetramethylammonium hydroxide, <1.0% polyalkylene glycol; liquid	Microposit MF-319 Developer	319, MF-319	STOCKED
Microposit MF-CD-26	95.0–99.0% water, 1.0–5.0% tetramethylammonium hydroxide; liquid	Microposit MF-CD-26 Developer	CD-26	STOCKED
Modified synthetic DNA	85–95% oligodeoxyribonucleic acid, unmodified; 5–15% nonradioactive modification (proprietary); solid	Modified synthetic DNA	modified oligodeoxyribonucleic acid, modify oligo, single-stranded DNA	
Nanozeolite	100% zeolites (crystalline alumiosilicates), composed of silica (SiO_2) and alumina (Al_2O_3), in various proportions plus metallic oxides; solid (powder)	Nanozeolite		RESTRICTED USE All processing must occur in Aisle 1 fumehood, with material in solution only.
Nanozeolite aqueous solution	5 wt.% nanozeolite, 95 wt.% water; liquid	Nanozeolite aqueous solution		RESTRICTED USE All processing must occur in Aisle 1 fumehood. Must be spun on in foil-lined Headway spinner.
Nanozeolite aqueous solution	5 wt.% nanozeolite, 95 wt.% water; liquid	Nanozeolite in water solution		RESTRICTED USE All processing must occur in Aisle 1 fumehood. Must be spun on in foil-lined Headway spinner.
Nickel oxide	100% nickel oxide; solid	Nickel oxide	NiO, nickel (II) oxide	RESTRICTED

Nitric Acid	Nitric Acid (HNO)	Nitric Acid	Aqua Fortis, Azotic Acid	STOCKED RESTRICTED USE
Nitrogen	100% Nitrogen; gas	Nitrogen	Dinitrogen, Refrigerant R728, Nitrogen, Medipure® Nitrogen, Extendapak Nitrogen	
Nitrous Oxide	99.5 - 100% Nitrous Oxide; gas	Nitrous oxide	Dinitrogen oxide / Laughing gas / Nitrogen oxide (N2O)	
Novec Engineered Fluid 7100DL	20–80% methyl nonafluoroisobutyl ether, 20–80% methyl nonafluoroisobutyl ether; liquid	Novec Engineered Fluid 7100DL		
Novec Engineered Fluid 7200DL	55–90% ethyl nonafluoroisobutyl ether, 10–45% ethyl nonafluorobutyl ether; liquid	Novec Engineered Fluid 7200DL		
Octafluorocyclobutane (C4F8)	100% Octafluorocyclobutane	Octafluorocyclobutane - C_4F_8	C_4F_8, Refrigerant C318, R C318	STOCKED
Oxygen	100 % Oxygen	Oxygen - Ox	Oxygen, Compressed; MediPure Oxygen; Aviator's Breathing Oxygen; USP Oxygen; Oxygen - Diving Grade	STOCKED RESTRICTED USE
Paralyne C (DPX-C)		Paralyne C (DPX-C)	Parylene C, Dichlorotricyclo[8.2.2.24,7] hexadeca-1(12),4,6,10,13,15-hexaene, mixed isomers, Chloro-p-xylylene cyclic dimer; Dichlorodi-1,4-xylylene; Dichlorotricyclo (8.2.2.2(sup 4,7))hexadeca-4,6,10,12,13,15-hexaene	STOCKED
Paralyne N (DPX-N)		Paralyne N (DPX-N)	Parylene N; 2,2 – paracyclophane, Cyclobis (benzene-1,4-dimethylene); Di-1,4-xylylene	STOCKED
PCE12 polymer	100% Poly[(2,6-(4,8-bis(5-(2-ethylhexyl)thiophen-2-yl)-benzo[1,2-b:4,5-b']dithiophene))-alt-(5,5-(1',3'-di-2-thienyl-5',7'-bis(2-ethylhexyl)benzo[1',2'-c:4',5'-c']dithiophene-4,8- dione)]; solid	PCE12 polymer	PBDB-T	
PDMS Base	Mixture	SYLGARD (R) 184 SILICONE ELASTOMER KIT (BASE)	PDMS	STOCKED
PDMS Curing Agent	Mixture	SYLGARD (R) 184 SILICONE ELASTOMER KIT (Curing Agent)		STOCKED
PEDOT:PSS aqueous solution	1–5% poly(3,4-ethylenedioxythiophene)-poly (styrenesulfonate), 95–99% water; liquid	PEDOT:PSS aqueous solution		

PEDOT: PSS-PEO aqueous solution	1.1% poly(3,4-ethylenedioxythiophene)-poly (styrenesulfonate), 11% poly(ethylene oxide), 87.9% water; liquid	PEDOT: PSS-PEO aqueous solution		
Pentane	Pentane	Pentane	AMYL HYDRIDE, normal pentane, n-Pentane	STOCKED
Phosphoric Acid	Phosphoric acid, water	Phosphoric Acid	Ortho-phosphoric acid	STOCKED RESTRICTED USE
PI-2574 polyimide precursor	10–30% Polyamic acid of Benzophenone Tetracarboxylic Dianhydride/4,4-Oxydianiline/m-Phenylenediamine Polymer, >60% n-Methylpyrrolidone; liquid	PI-2574 polyimide precursor	Pyralin® polyimide precursor coatings	
Planarizing coating PC43-700	>80% cyclohexanone, <20% resins (proprietary), 1–5% additives (proprietary); liquid	Planarizing Coating PC43-700		
PMGI SFG Slow Series Resists	65–85% cyclopentanone, 10–15% 1-methoxy-2-propanol, 0.2–20% polyaliphatic imide copolymer; liquid	PMGI SFG Slow Series Resists	PGMI	
PMMA 950k	1–15% poly(methylmethacrylate), 85–99% anisole; liquid	Organic Polymer Solution / 950 PMMA Series Resists in Anisole	PMMA, PMMA 950	STOCKED
Poly(4-vinylpridine)	100% poly(4-vinylpyridine); solid	Poly(4-vinylpridine)	P4VP	RESTRICTED USE All processing must occur in Aisle 1 fumehood, with material in solution only.
Poly(4-vinylpridine) solution in IPA	5 wt.% poly(4-vinylpyridine), 95 wt.% isopropyl alcohol; liquid	Poly(4-vinylpridine) solution in IPA		RESTRICTED USE
Poly (ethyleneimine) aqueous solution	50% aziridine (homopolymer), 50% water; liquid	Poly (ethyleneimine) aqueous solution	Ethyleneimine polymersolution, PEI	RESTRICTED USE
Poly (vinyl alcohol) aqueous solution	5% polyvinyl alcohol, 95% water; liquid	Poly (vinyl alcohol) aqueous solution	PVA, vinyl alcohol, ethenol, hydroxyethene	
Poly (vinyl chloride)	100% poly(vinyl chloride); solid	Poly(vinyl chloride)	PVC	
Polyacrylamide	100% polyacrylamide; solid	Polyacrylamide		

Polyacrylamide aqueous solution	5 wt.% polyacrylamide, 95 wt.% water; liquid	Polyacrylamide aqueous solution		RESTRICTED USE All processing must occur in Aisle 1 fumehood. Must be spun on in foil-lined Headway spinner.
Polystyrene	100% polystyrene; solid	Polystyrene	Polyvinylbenzene, PS	
Polystyrene solution in toluene	5–10 wt.% polystyrene, 90–95 wt.% toluene; liquid	Polystyrene solution in toluene		RESTRICTED USE All processing must occur in Aisle 1 fumehood. Must be spun on in foil-lined Headway spinner.
Potassium chloride	100% potassium chloride; solid (granular)	Potassium chloride	KCl, muriate of potash	
Potassium hydroxide	Potassium Hydroxide, Water	Potassium Hydroxide Solution 45%	KOH, caustic potash, potassium hydrate	STOCKED
Potassium Iodate	Iodic acid (HIO3), potassium salt	Potassium Iodate	Iodic acid, potassium salt	STOCKED
ProTEK B3-25	30–40% ethyl-3-ethoxypropionate, 30–40% 5-methyl-2-hexanone, 20–30% polymer solids (proprietary); liquid	ProTEK B3-25		RESTRICTED USE
ProTEK B3 Primer	95–100% 1-methoxy-2-propanol, <1–5% deionized water, <1% additive (proprietary); liquid	ProTEK B3 Primer		RESTRICTED USE
ProTEK Remover 100	100% 5-methyl-2-hexanone; liquid	ProTEK Remover 100	MIAK, methyl isoamyl ketone	RESTRICTED USE
PVC in MIBK solution	5–20 wt.% poly(vinyl chloride), 80–95 wt.% methyl isobutyl ketone; liquid	PVC in MIBK solution		RESTRICTED USE All processing must occur in Aisle 1 fumehood. Must be spun on in foil-lined Headway spinner.
Rb/Amax pill	56% zirconium, 33% rubidium molybdate, 11% aluminum; solid	Rb/Amax pill	rubidium dispenser	RESTRICTED USE
Remover PG	99–99.5% N-methyl-2-pyrrolidinone, 0.1–1.0% proprietary surfactant; liquid	Remover PG		STOCKED
Ruthenium	100% ruthenium; solid	Ruthenium	Ru	Deposition allowed in all sputtering systems.
Silane	SiH	Silane	Monosilane, silicon hydride, silicon tetrahydride, silicane	STOCKED RESTRICTED USE
Silver Etchant TFS	2–4% iodine, 40–45% potassium iodide, 51–58% water; liquid	Silver Etchant TFS		
SU-8 2000 series photoresist	23–96% cyclopentanone, 0.3–5% mixed triarylsulfonium/hexafluoroantimonate salt, 0.3–5% propylene carbonate, 3–75% epoxy resin; liquid	SU-8 2000 Series Resists	SU-8	STOCKED

SU-8 Developer	99.5–100% 1-methoxy-2-propanol acetate, 0–0.5% 2-methoxy-1-propyl acetate; liquid	SU-8 Developer	PGMEA	STOCKED
SUEX Series TDFS		SUEX Series TDFS	SUEX	STOCKED
Sulfur Hexafluoride	100% Sulfur Hexafluoride	Sulfur Hexafluoride - SF6		STOCKED RESTRICTED USE
Sulfuric Acid	Sulfuric Acid / Water	Sulfuric Acid H_2SO_4	Oil of vitriol, babcock acid, sulphuric acid	STOCKED RESTRICTED USE
SurPass 3000	<1% ethylene glycol, <1% octoxinol, 98% water; liquid	SurPass 3000		STOCKED
tesa 61504 desiccant tape	Release liner: PET foil, single-side siliconized Adhesive: Mixture comprising synthetic rubber and resins	tesa 61504 desiccant tape		RESTRICTED USE
Tetrabutylammonium fluoride solution	75% tetrabutylammonium fluoride, 25% water; liquid	Tetrabutyl ammonium fluoride solution	TBAF solution	STOCKED
Tetraethyl Orthosilicate (TEOS)		Tetraethyl Orthosilicate (TEOS)	TEOS, Tetraethoxysilane, Ethyl Silicate, Tetraethyl Silicate	STOCKED RESTRICTED USE
Tetrafluoromethane Halocarbon 14	100% Tetrafluoromethane	Tetraflouromethane (CF4) Halocarbon 14	Tetrafluoromethane (R14), Carbon tetrafluoride, F-14, refrigerant gas R14, perfluoromethane, halon-14	STOCKED RESTRICTED USE
Tin Oxide /Indium Tin Oxide Etchant TE-100	25–35% ferric chloride, 3–4% hydrochloric acid, >60% water; liquid	Tin Oxide /Indium Tin Oxide Etchant TE-100	tin etch, ITO etch	
TMAH	mixture	Tetramethylammonium Hydroxide in water	TMAH, TMAOH	STOCKED RESTRICTED USE
Toluene	100% toluene	Toluene	methylbenzene, toluol, phenylmethane	RESTRICTED USE All processing must occur in Aisle 1 fumehood.
Trichloro(1H, 1H,2H, 2H-perfluorooctyl) silane	100% trichloro(1H,1H,2H,2H-perfluorooctyl)silane; liquid	Trichloro (1H,1H, 2H,2H-perfluorooctyl)silane	Trichloro(3,3,4,4,5,5,6,6,7,7,8,8,8-tridecafluorooctyl)silane, 1h,1h,2h,2h-Perfluorooctyltrichlorosilane, Trichloro (3,3,4,4,5,5,6,6,7,7,8,8,8-tridecafluorooctyl) silane	STOCKED
Trichloromethylsilane (TMCS)	100% trichloromethylsilane; liquid	Trichloromethylsilane	TMCS, trimethylsilyl chloride, chlorotrimethylsilane	STOCKED RESTRICTED USE

Trifluoromethane Halocarbon 23	100% Halocarbon 23	Trifluoromethane (CHF3) Halocarbon 23		STOCKED RESTRICTED USE
Tris-EDTA 100X Solution	85% water, 12.1% tris (hydroxymethyl) aminomethane, 2.9% ethylenediamine tetraacetic acid, <1% hydrochloric acid; liquid	Tris-EDTA 100X Solution	Tris(hydroxymethyl)aminomethane-EDTA solution	
Yttria stabilized zirconia	78–94% zirconium oxide, 4–20% yttrium oxide, 1–2% hafnium oxide, 0–3% aluminum oxide; solid	Yttria stabilized zirconia (evaporation material)	YSZ, yttrium stabilized zirconium oxide, zirconium (IV) oxide - yttria stabilized	
ZED-N50	100% pentyl acetate; liquid	ZED-N50	n-amyl acetate	STOCKED
ZEP 520A	88.5–89.5% anisole, 10.5–11.5% methyl styrene/chloromethyl acrylate copolymer; liquid	ZEP 520A	ZEP	STOCKED
ZEP-A	100% anisole; liquid	ZEP-A	anisole, methoxybenzene, methyl phenyl ether	STOCKED